

# LOCTITE ABLESTIK 6202CB

August 2012

# PRODUCT DESCRIPTION

LOCTITE ABLESTIK 6202CB provides the following product characteristics:

Technology	Proprietary Hybrid Chemistry	
Appearance	Yellow	
Filler Type	Silica and Rubber	
Cure	Heat cure	
Product Benefits	Stencil printing	
	<ul> <li>Low moisture uptake</li> </ul>	
	<ul> <li>Low flow (&lt;150µm)</li> </ul>	
	Low warpage	
	Long work life	
	Low modulus	
Application	Die attach	
Substrates	Laminate	
Typical Package	Chip scale packages and Stencil printing	
Application		

LOCTITE ABLESTIK 6202CB B-stageable adhesive is ideal for chip scale packages where tolerance and bleed need to be minimized. This low modulus adhesive is recommended for large die sizes.

#### TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	2.6
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):	
Speed 5 rpm	30,000
Work Life @ 25°C, days	14
Shelf Life (from date of manufacture):	
@ -20°C, days	183
@ -40°C, days	365
Flash Point - See SDS	

# TYPICAL PROCESS DATA

**Recommended B-Stage Condition** 

90 minutes @ 125°C

# **Pre-Dry Prior to Die Attach**

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5 minutes @ 125°C
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Recommeded when there is a significant amount of time (i.e., 4 hours or more) between B-stage and die attach.

### **Chip Attach**

Die Temperature, °C	130 to 160
Substrate Temperature, °C	25 to 50
Force, kg-f	2 to 6
Time, second	1

# TYPICAL CURING PERFORMANCE

# **Cure Schedule**

30 minute ramp to  $100^{\circ}$ C; 30 minutes @  $100^{\circ}$ C + 30 minute ramp from  $100^{\circ}$ C to  $175^{\circ}$ C; 60 minutes @  $175^{\circ}$ C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

# TYPICAL PROPERTIES OF CURED MATERIAL

## **Physical Properties**

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Coefficient of Thermal Expansion, :		
Below Tg, ppm/°C		70
Above Tg, ppm/°C		350
Glass Transition Temperature (Tg) by TMA,	40	
Tensile Modulus, DMTA :		
@ 25 °C	N/mm² (psi)	500 (72,500)
@ 150 °C	N/mm² (psi)	
@ 250 °C	N/mm² (psi)	6 (812)
Extractable Ionic Content, :		
Chloride (Cl-)		<25
Sodium (Na+)		<20
Potassium (K+)		<20
Water Extract Conductivity, µmhos/cm		120
Moisture Absorption @ Saturation, w 85°C/85°RH	wt.% @	1.03
Density before B-Stage, g/cc		1.10
Density after B-Stage, g/cc		1.15

# TYPICAL PERFORMANCE OF CURED MATERIAL

# Miscellaneous

Die Shear Strength :

2 X 2 mm , kg-f,		
Substrate	@25°C	@245°C
Si die to Ceramic	10.4	1.1

# **GENERAL INFORMATION**

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

# THAWING:

- 1. Allow container to reach room temperature before use.
- 2. After removing from the freezer, set the syringes to stand vertically while thawing.
- DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
- DO NOT re-freeze. Once thawed to 25°C, the adhesive should not be re-frozen.

# DIRECTIONS FOR USE

1. Apply enough adhesive to the stencil to ensure complete filling of the stencil with a 15 to 20 mm diameter bead. Typically, this requires 20 to 50 cc of adhesive, depending on the stencil size. For two-direction printing, double beading is recommended.



2. Unused adhesive may be re-frozen, provided the total time at ambient temperature does not exceed the recommended work life.

#### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

#### STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

# Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

#### Conversions

 $(^{\circ}C x 1.8) + 32 = ^{\circ}F$ kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb/F N/mm x 5.71 = lb/in psi x 145 = N/mm<sup>2</sup> MPa = N/mm<sup>2</sup> N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

# Disclaimer

#### Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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